

OFFICIAL

PATENT

Docket No.: JCLA8104

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**RECEIVED
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In re application of :

Applicant : PHILIP CHUNG-HWEI CHEN et al.

Application No. : 10/034,326

Filed : December 28, 2001

For : LOW-LEAD-CONTENT PLATING PROCESS

Art Unit : 1753

Examiner : WONG, EDNA

RESPONSE TO RESTRICTION REQUIREMENT**MAIL STOP Non-Fee Amendment**

Commissioner for Patents

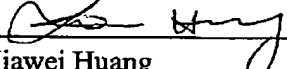
P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Restriction Requirement mailed on October 22, 2003 regarding the above-identified application, Applicant elects Group I, claims 1-4, for further examination on merits. Please cancel claims 5-9 without prejudice and disclaimer.

No fee is believed to be due in connection with the filing of this paper. However, the Commissioner is authorized to charge any additional fees that may be required to Account No. 50-0710 (Order No. JCLA8104).

Respectfully submitted,
J.C. PATENTSDated: 10/31/2003By: 
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